

10th Conference on PET, SPECT, and MR Multimodal Technologies, Total Body and Fast Timing in Medical Imaging

NUV-sensitive Deep-Junction (NUV-DJ) SiPMs, a new technology optimized for fast timing applications

O. A. Marti Villarreal^{1,}, Fabio Acerbi¹, Giovanni Paternoster¹, Michele Penna^{1,2}, Nicola Zorzi¹, and Alberto Gola¹*

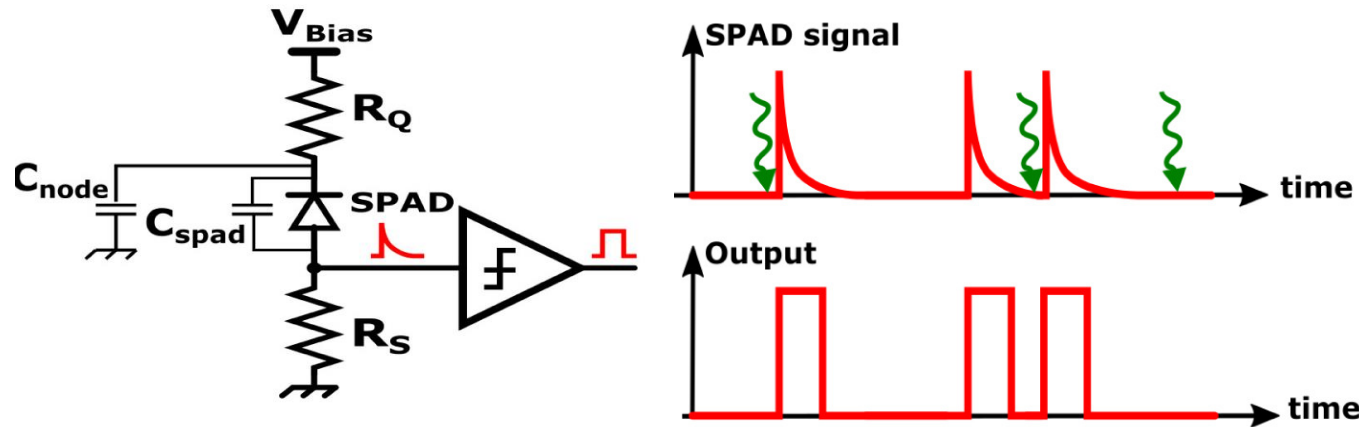
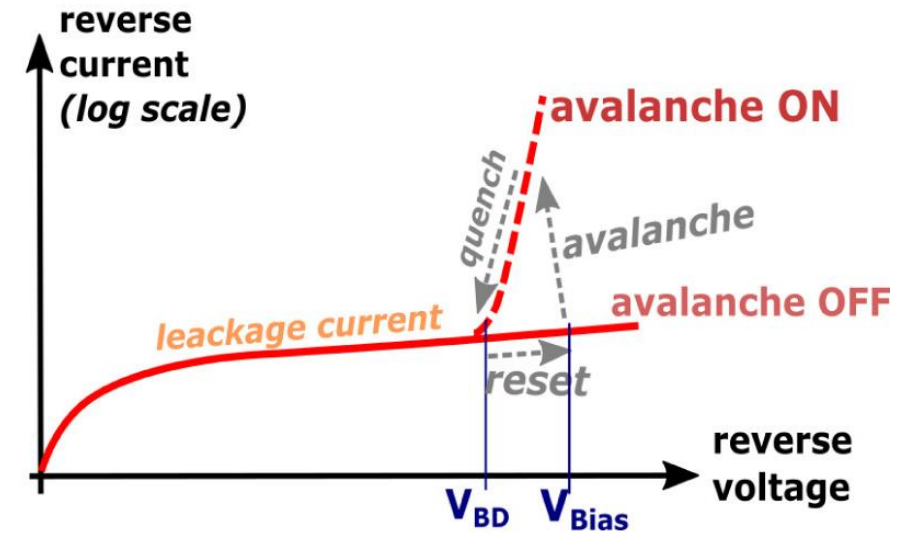
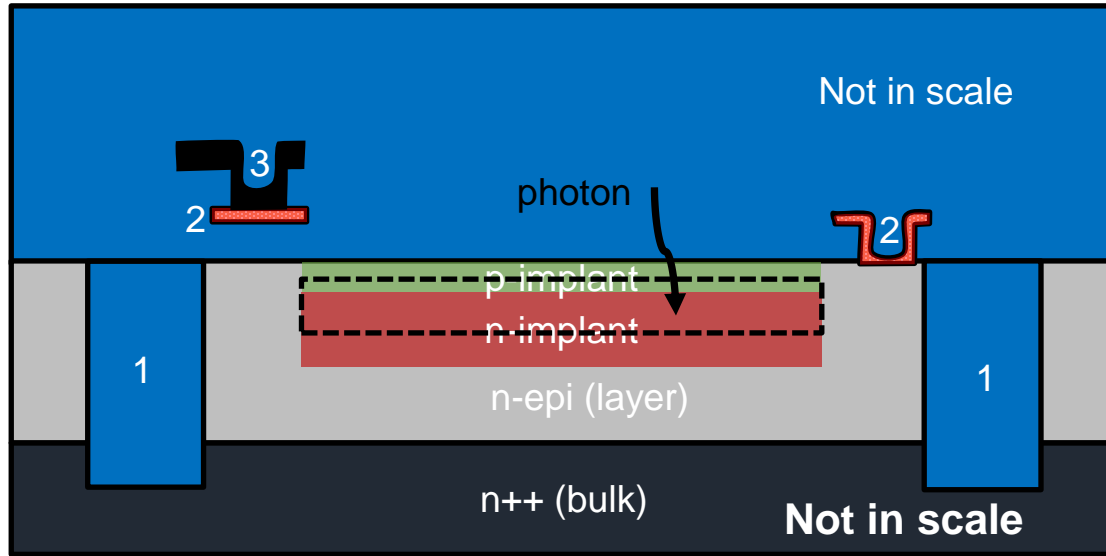
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Outline

- **Single Photon Avalanche Diode (SPAD) & Silicon Photomultipliers (SiPMs)**
- **SiPMs technologies on FBK**
- **Near-Ultraviolet sensitive Deep-Junction (NUV-DJ) SiPMs**
- **Experimental characterization of the first production of NUV-DJ technology**
- **Remarks and Conclusions**

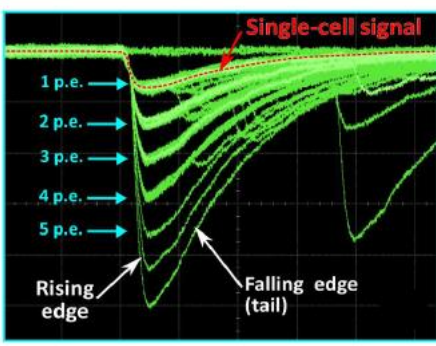
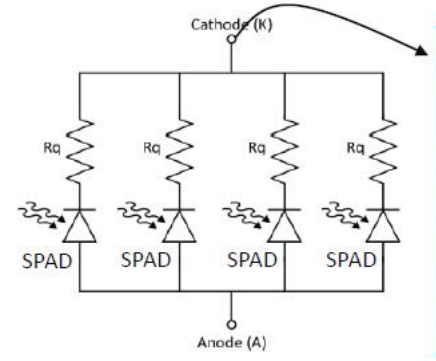
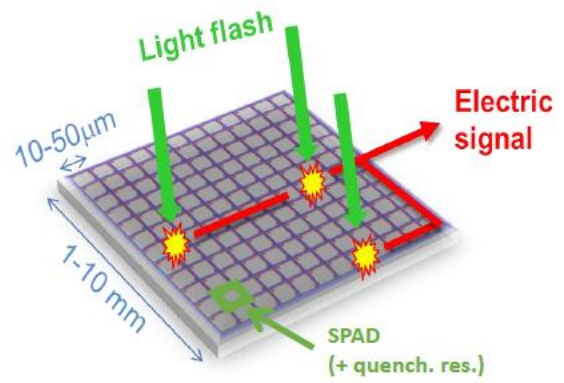
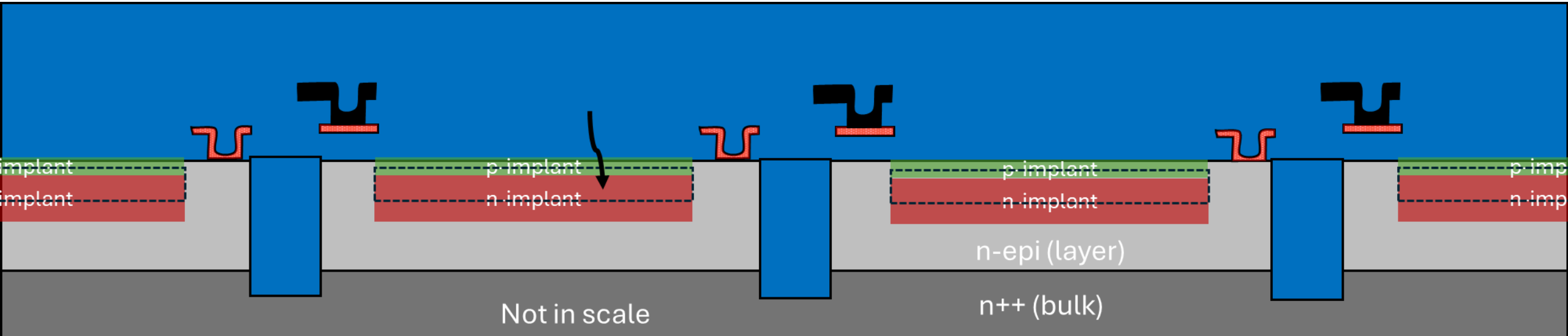
Single Photon Avalanche Diode (SPAD)



- 1-) Deep trench isolation
 - 2-) Polysilicon quenching resistor
 - 3-) Metal connection to the readout pad
-  → High-field region

*Acerbi, Fabio, and Stefan Gundacker. "Understanding and simulating SiPMs." *Nuclear Instruments and Methods in Physics Research Section A: Accelerators, Spectrometers, Detectors and Associated Equipment* 926 (2019): 16-35.

Silicon Photomultipliers (SiPMs)



Silicon Photomultiplier (SiPM) main features:

- Single-photon sensitive detectors with an excellent Single photon time resolution (few tens of ps)
- Can cover large-areas ($1 \times 1 \text{ mm}^2$ up to $10 \times 10 \text{ mm}^2$)
- Low bias voltage (Lower power consumption)
- Compactness and Robustness
- Insensitive to magnetic fields

Applications: medical imaging, high-energy physics, biotech, LiDAR, diffuse optics, others.

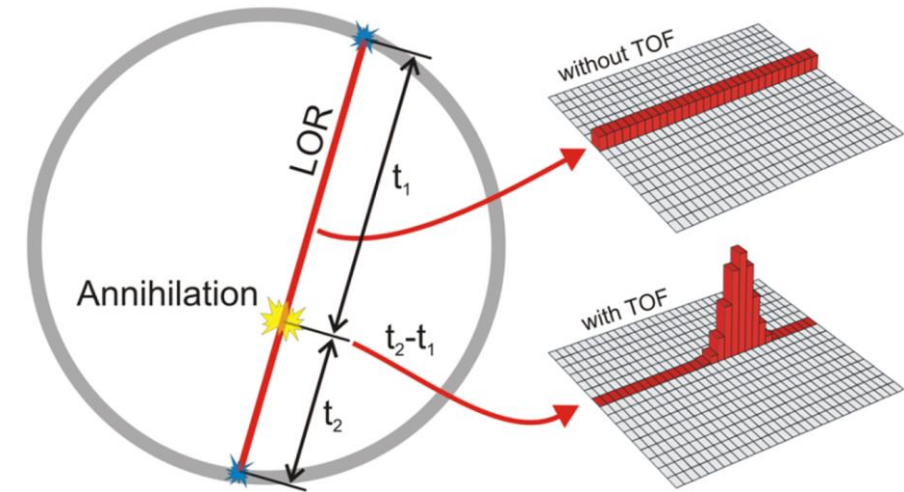
Time-Of-Flight PET (ToF-PET) systems

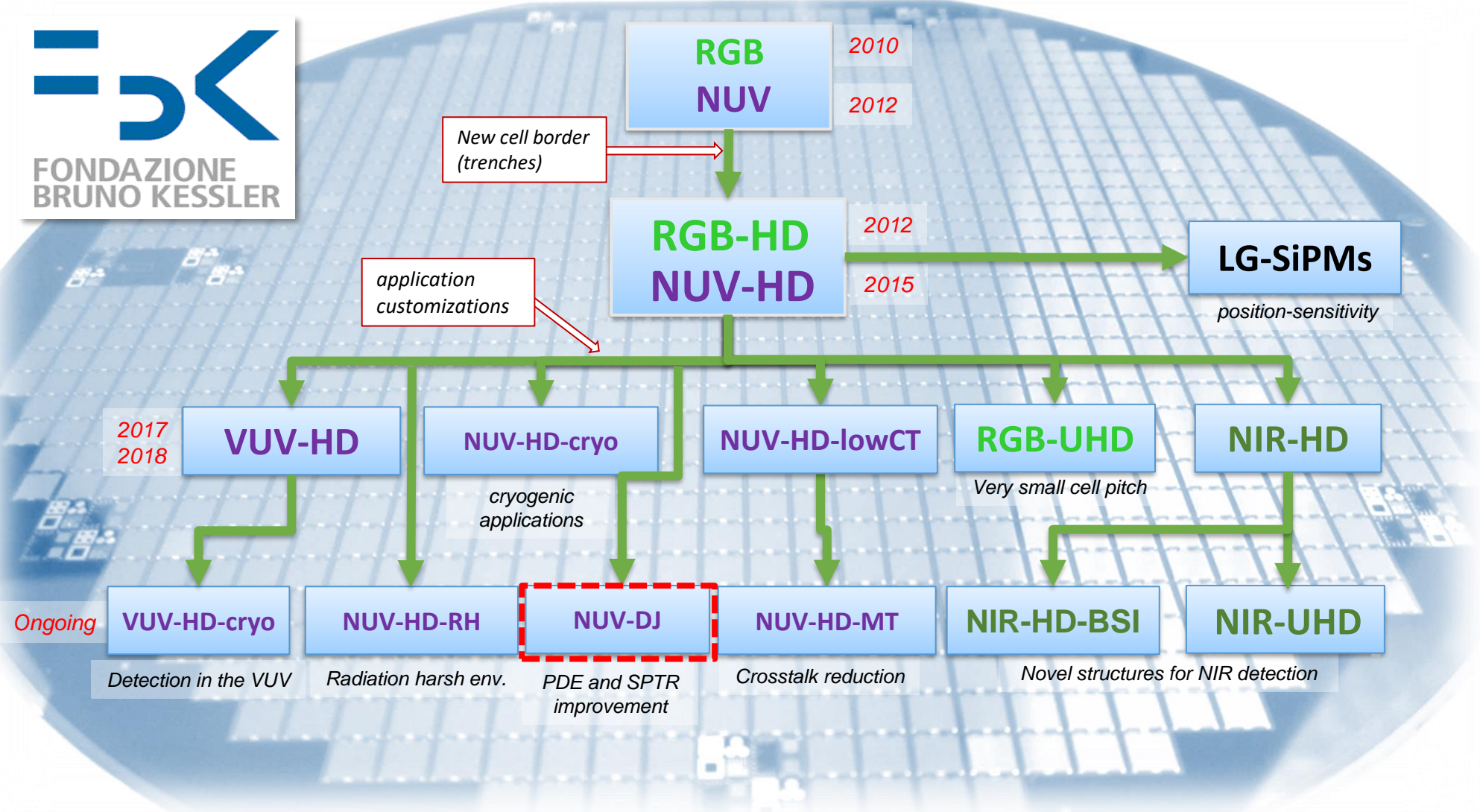
-Improved spatial resolution compared to standard PET systems

- Faster acquisition
- Lower dose to the patient
- Better diagnosis

SiPM detector main requirements:

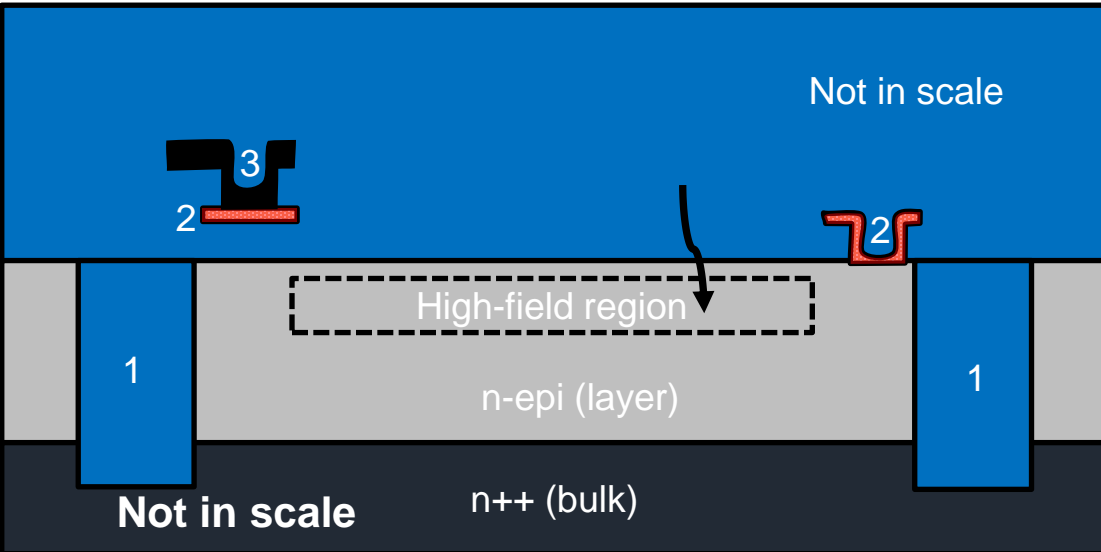
- Fast timing (Coincidence time resolution (CTR)) (< 100 ps)
- High Photon Detection Efficiency (PDE) ($> 60\%$) for a scintillator peak wavelength emission of 420 nm (For LYSO scintillators)



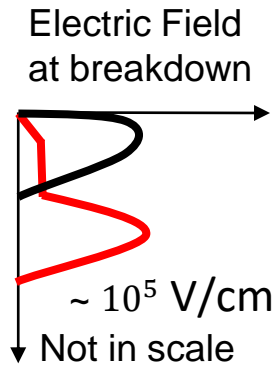
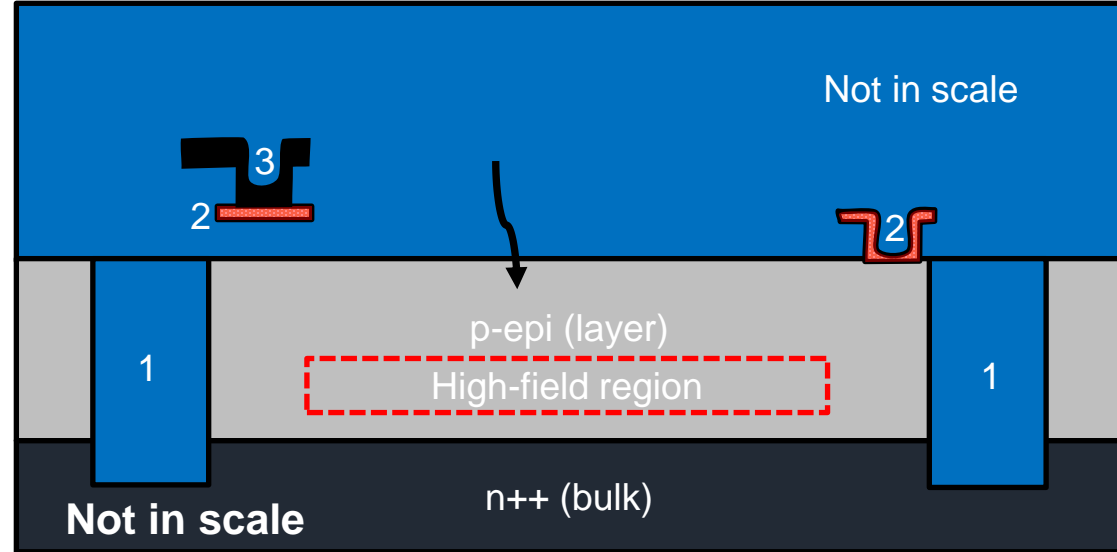


Near-Ultraviolet sensitive Deep-Junction (NUV-DJ) SiPMs*

Microcell (SPAD) of FBK NUV-HD technology



Microcell (SPAD) of FBK new NUV-DJ technology



- 1-) Deep trench isolation
- 2-) Polysilicon quenching resistor
- 3-) Metal connection to the readout pad

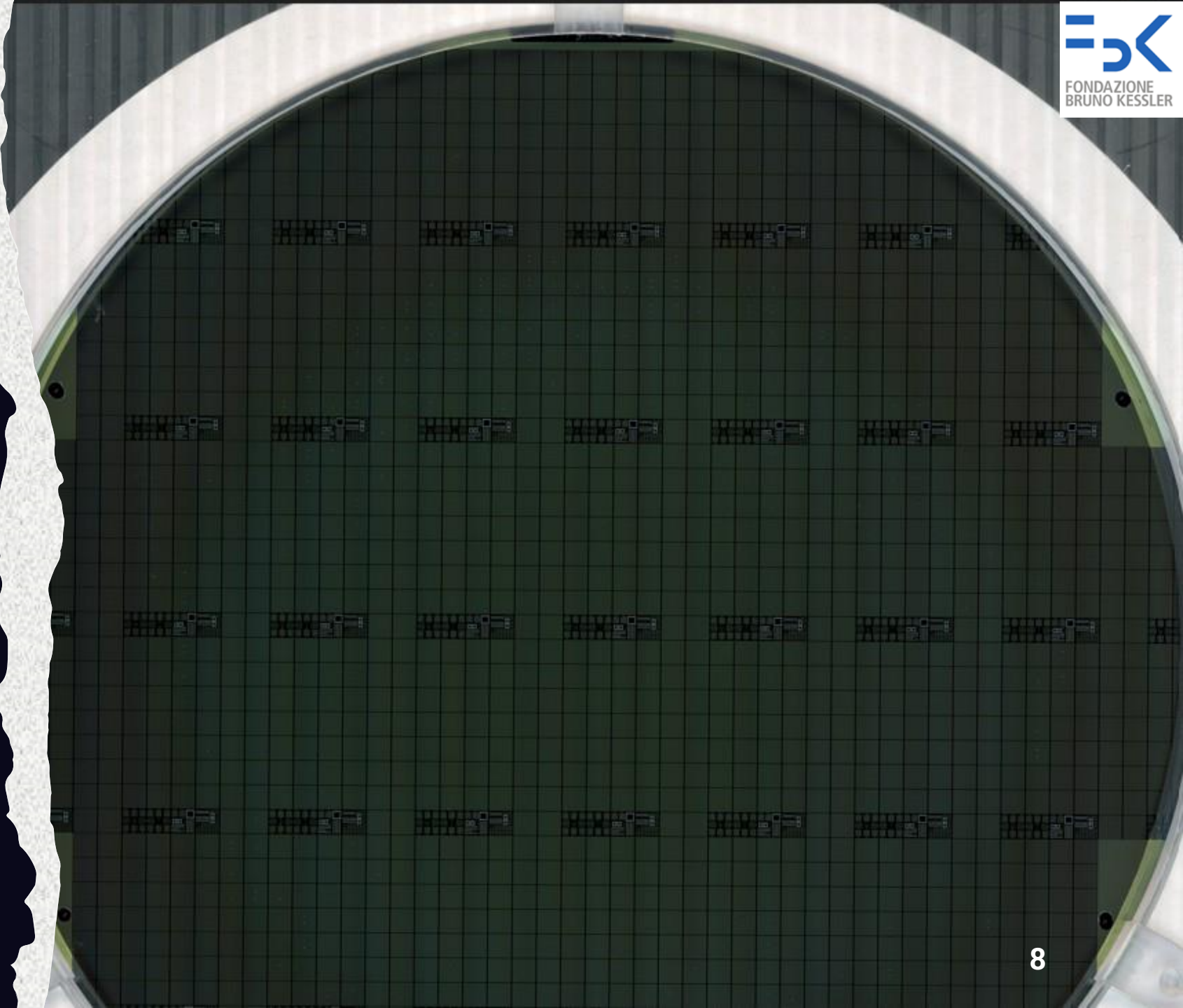
NUV-HD (SPAD) ———

NUV-DJ (SPAD) ———

*The illustration of the Electric Field at breakdown for both technologies is only illustrative

General description of the first production (It was used an external silicon foundry)

- 8-inch wafers
- Total wafers: few tens
- Layout split: 26
- Process split: >10 (different implants energies, doses, and thermal budget)
- Three different epi thicknesses: few micrometers
- n++ bulk: low resistivity
- p-type epitaxial layer: high resistivity
- SPAD pitch: $40\ \mu\text{m}$
- SiPM dimension: $4\times 4\ \text{mm}^2$, $1\times 1\ \text{mm}^2$
- Some test structures were added with different geometries



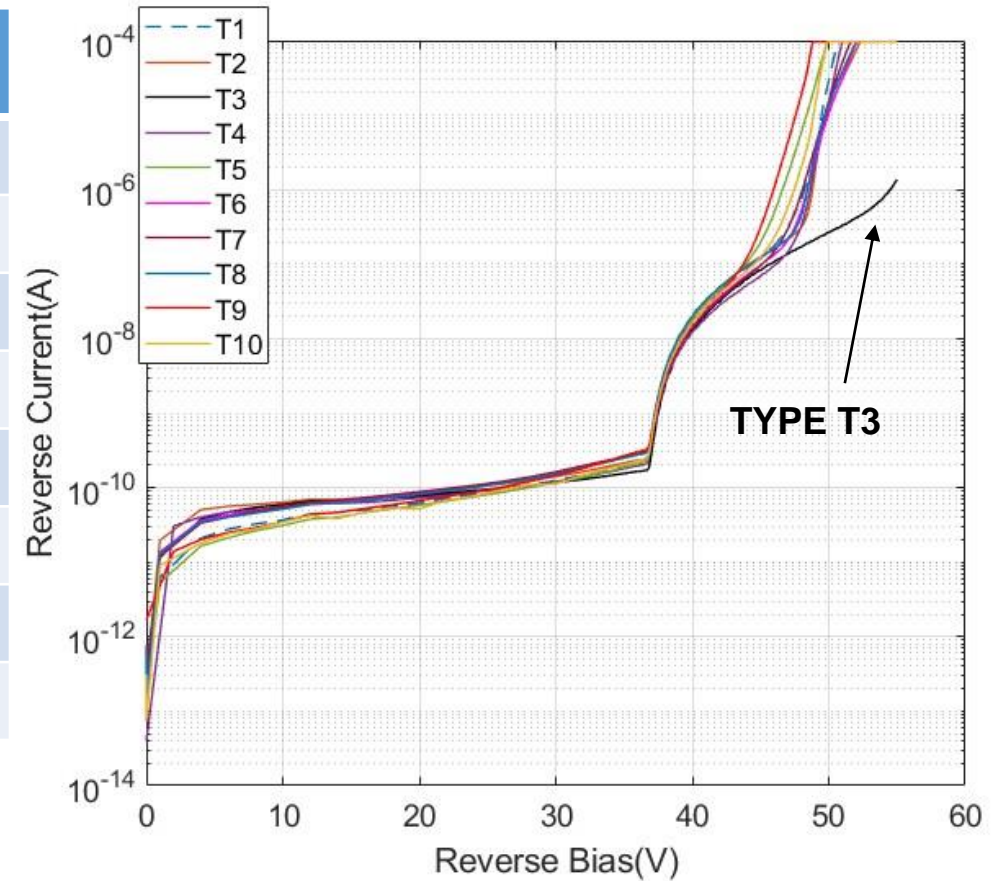
Experimental characterization of the first production of NUV-DJ technology

Main process split

Process split	Epi (p-type) thickness	High-Field region depth (D1 < D2, etc...)	Deep implant (DI) dose
1	Thin	D1	Low
2	Thin	D1	Medium
3	Thin	D1	High
4	Thin	D2	Low
5	Thin	D2	Medium
6	Thin	D2	High
7	Thick	D3	Medium
8	Thick	D4	Medium

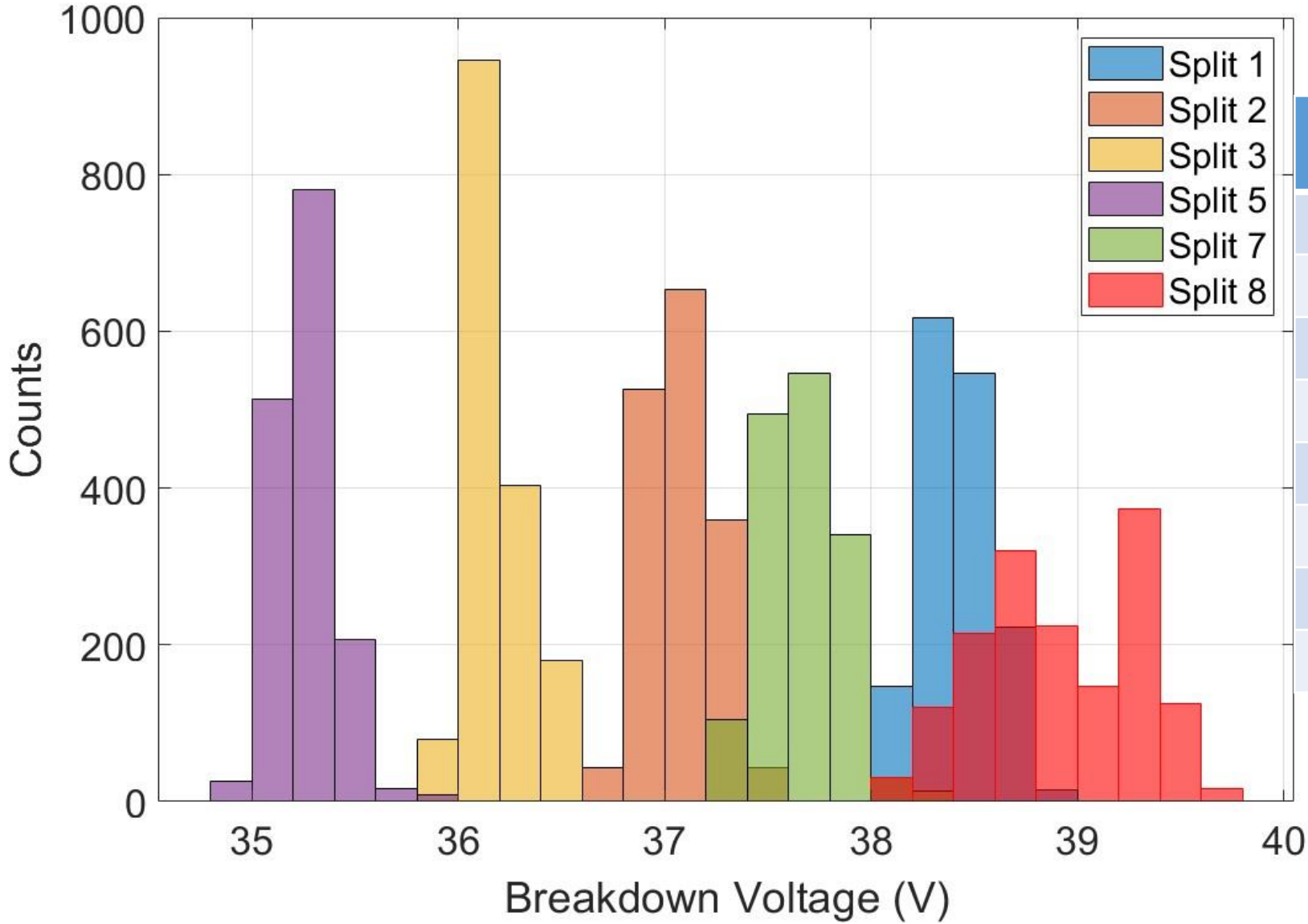
Design*	Total	Nominal Fill Factor (%)
Aggressive	10	80.8
Moderate	8	76.9
Safe	8	72.9

Example of I(V) for the Aggressive design (Split 2)



*Distance from the High-Field region to the Trench

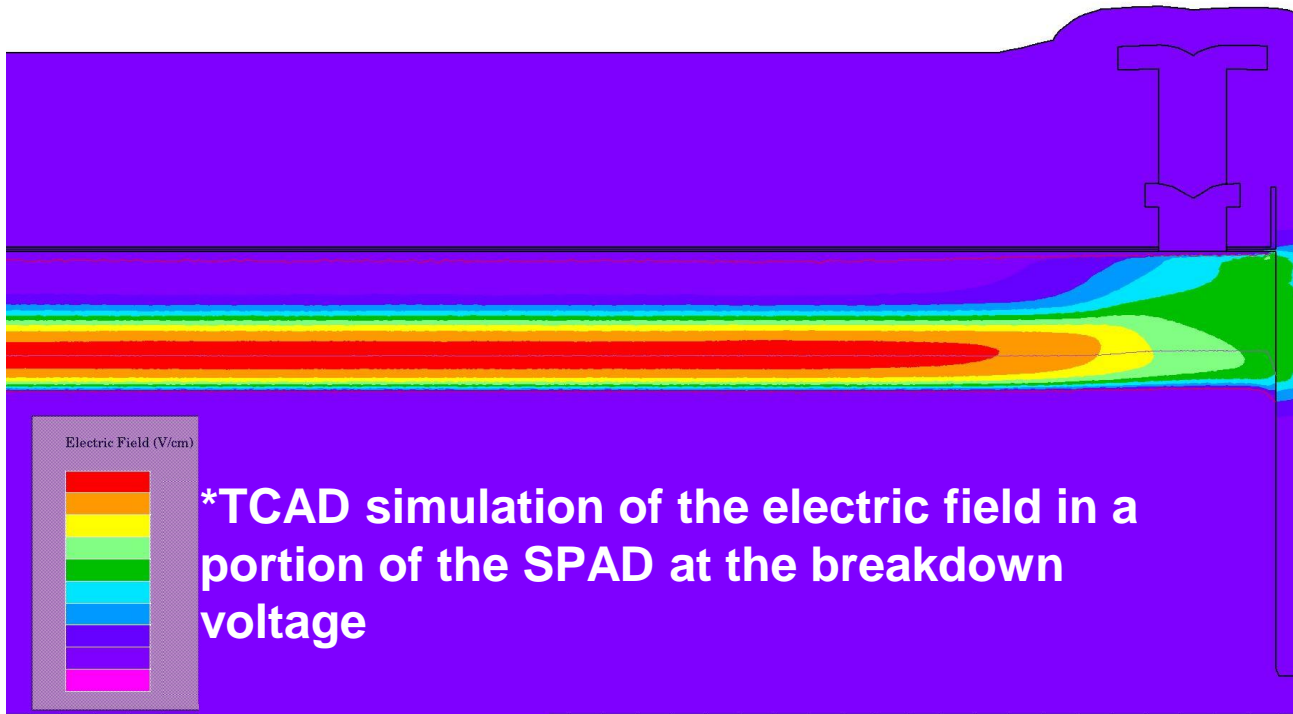
Breakdown Voltage (24 °C)



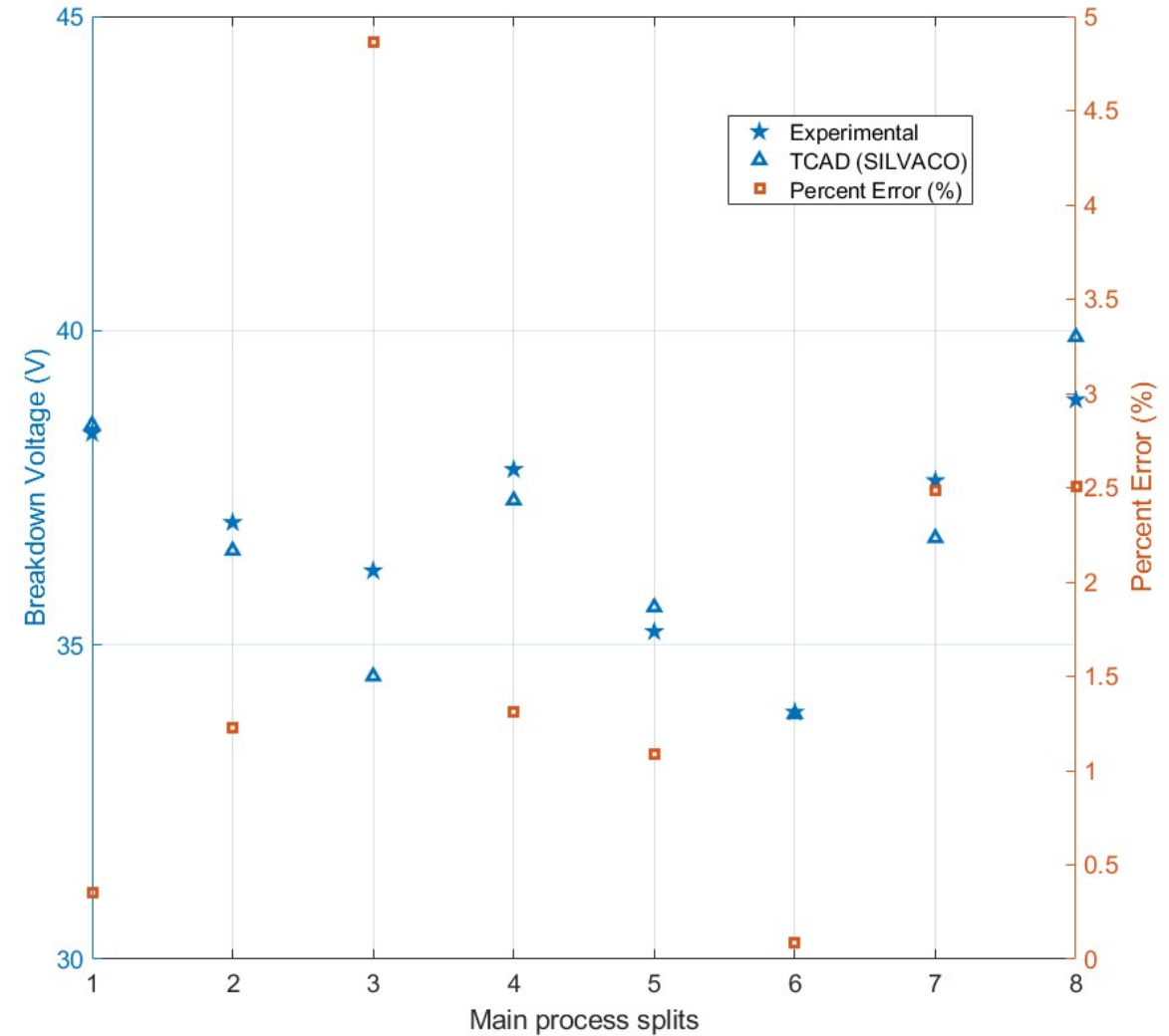
Process split	Epi (p-type) thickness	High-Field region depth (D1 < D2, etc...)	Deep implant (DI) dose
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2	Thin	D1	Medium
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4	Thin	D2	Low
5	Thin	D2	Medium
6	Thin	D2	High
7	Thick	D3	Medium
8	Thick	D4	Medium

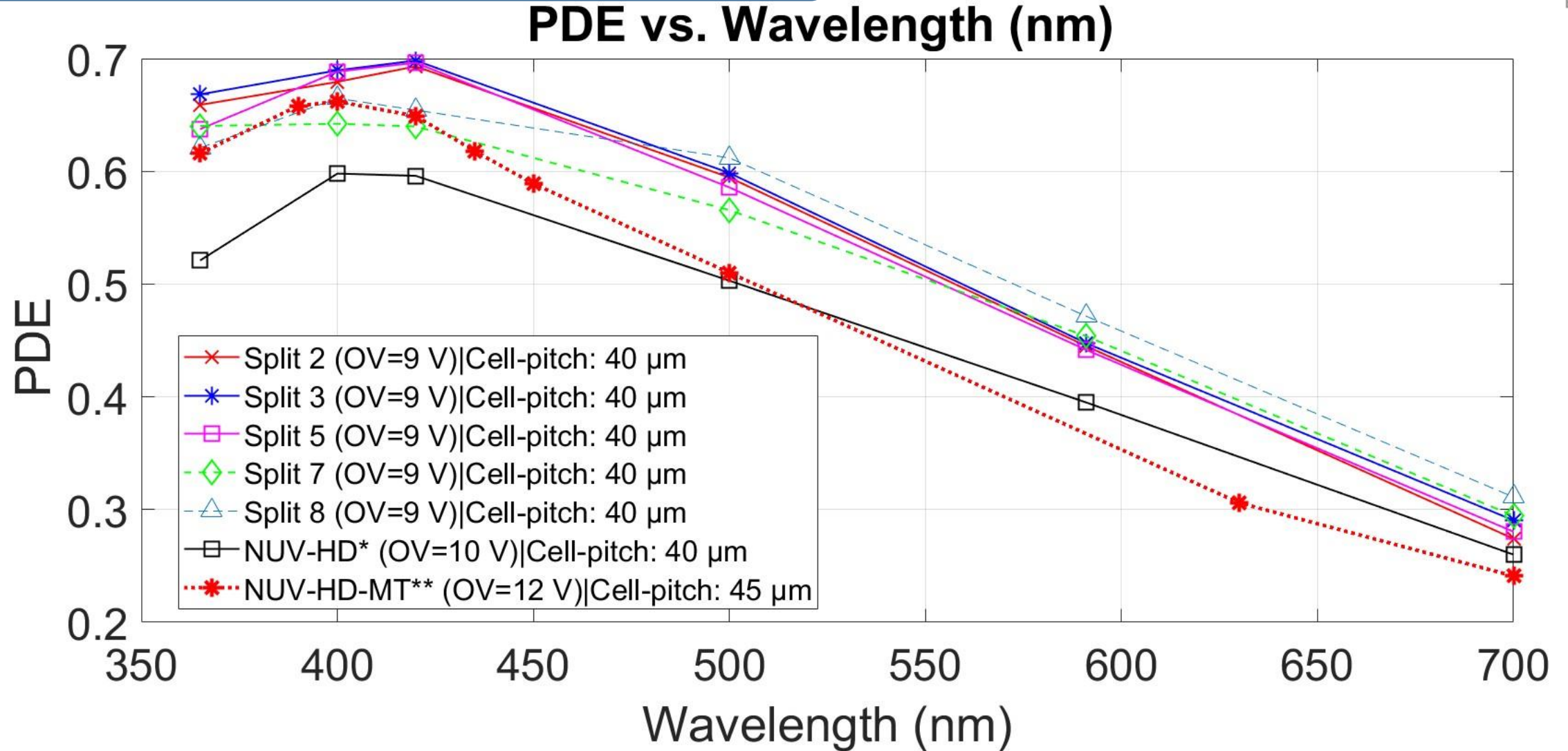
Yield > 90% (All splits)

Breakdown Voltage (V) study



Process split	Breakdown Coefficient (mV/°C)	Activation Energy (Ea) at 5 V of overvoltage
2	34.09	0.632
5	44.50	0.638
6	37.09	0.649

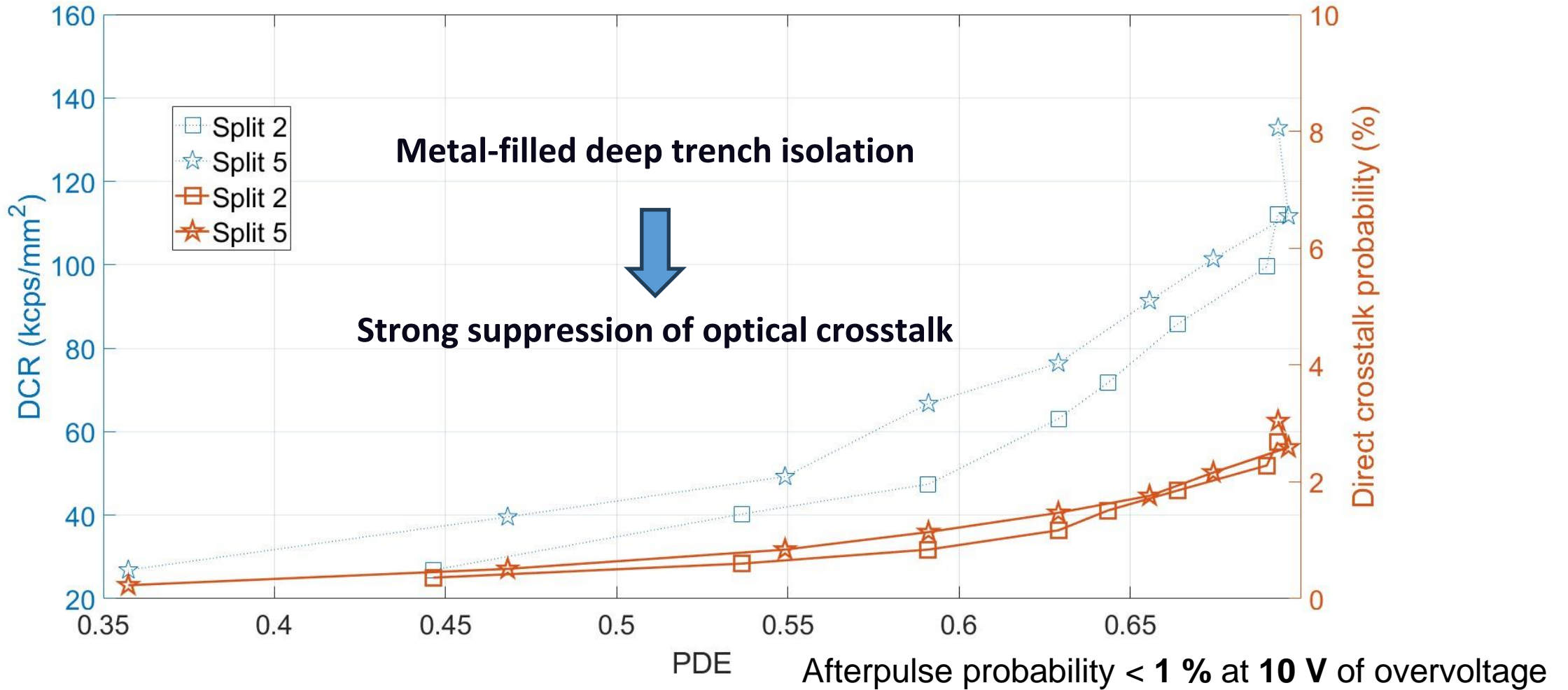




*Gola, Alberto, et al. "NUV-sensitive silicon photomultiplier technologies developed at Fondazione Bruno Kessler." *Sensors* 19.2 (2019): 308.

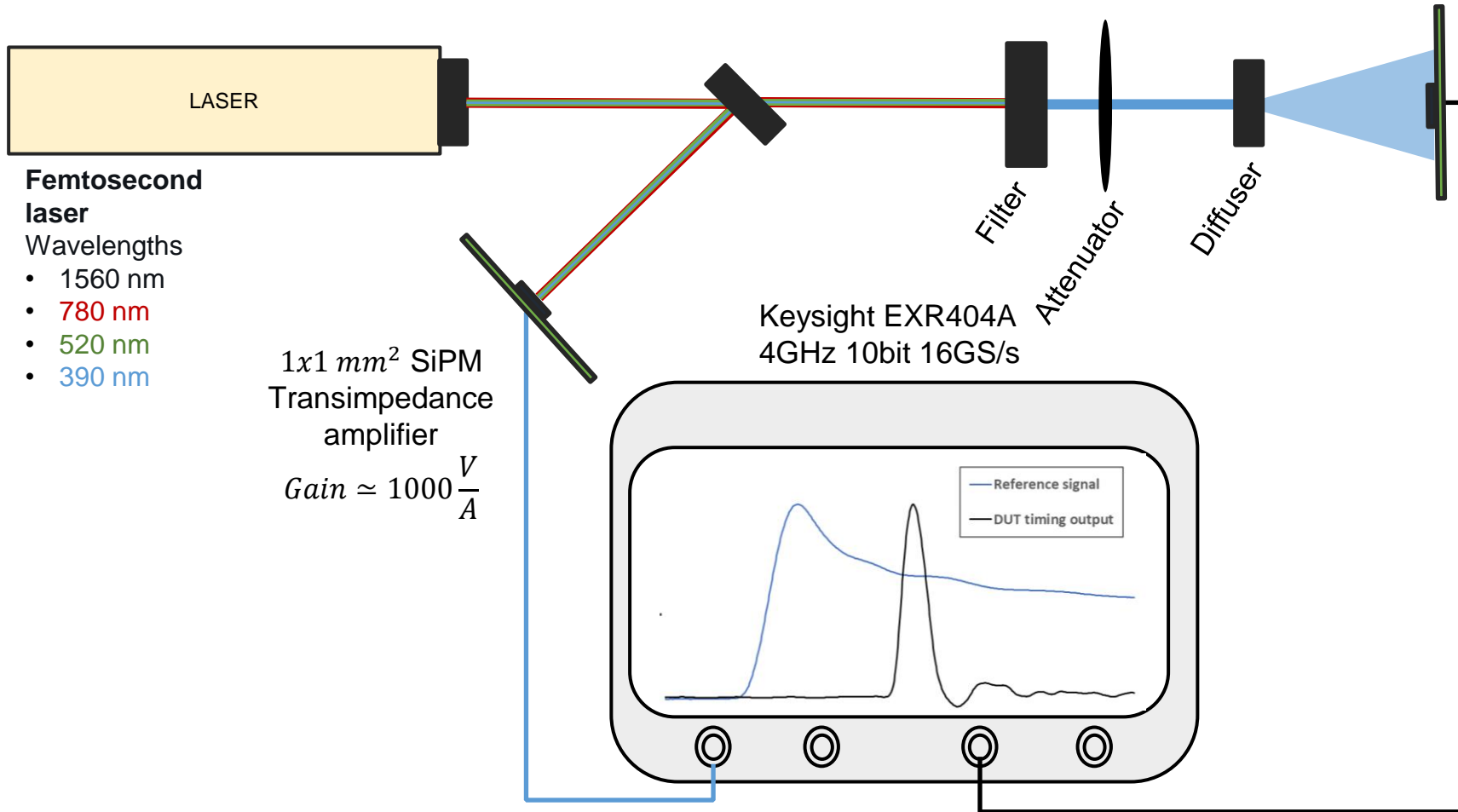
**Merzi, Stefano, et al. "Nuv-hd sipms with metal-filled trenches." *Journal of Instrumentation* 18.05 (2023): P05040.

Noise parameter as function of the PDE

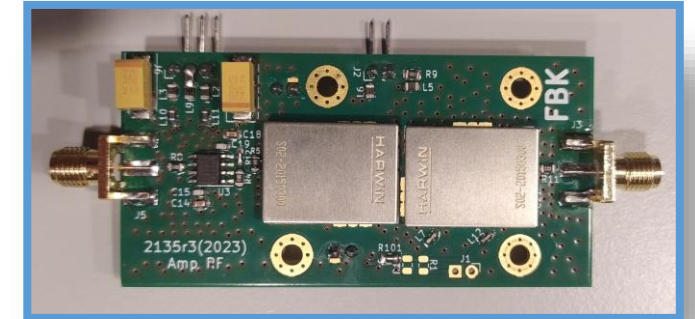


Single Photon Time Resolution (SPTR)

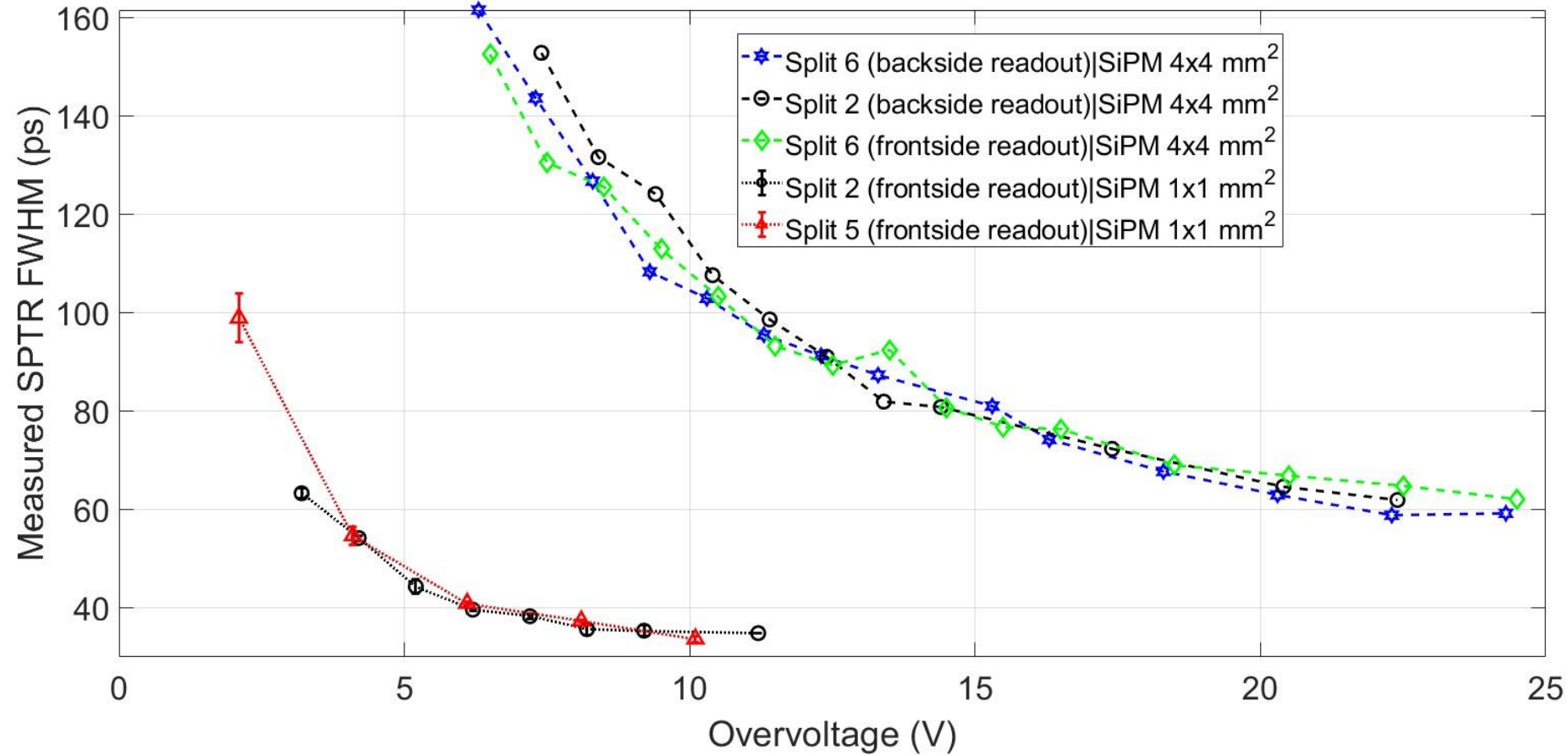
Experimental setup

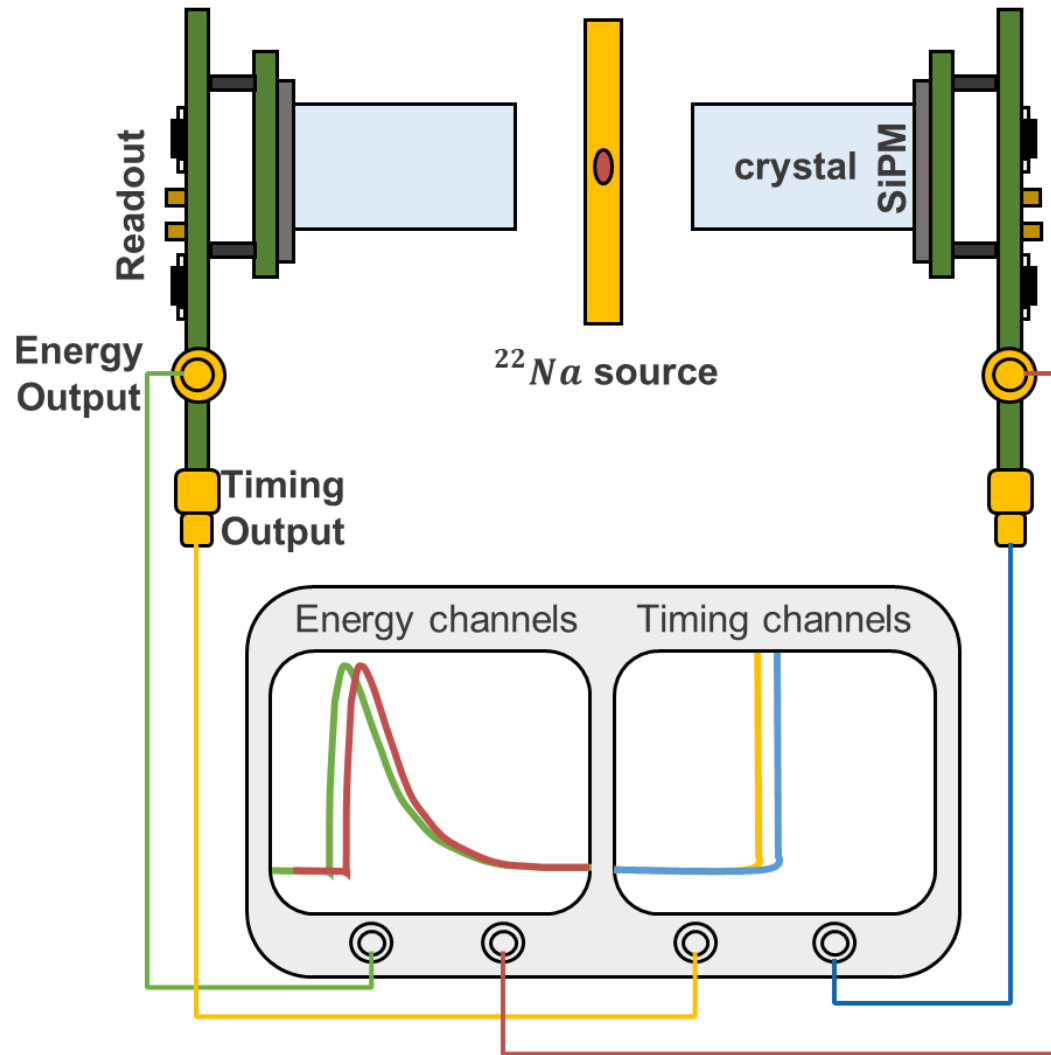


HF readout developed at FBK
Implemented with BGA61



SPTR measurements have been performed with blue light (390nm)





- Two SiPMs coupled with $2.76 \times 2.76 \times 18 \text{ mm}^3$ LYSO:Ce crystal
- The crystals were wrapped in Teflon and glued on the SiPMs with optical glue Meltmount ($n = 1.58$)
- Motorized steppers for alignment in two axis
- A High Frequency readout was used [1,2]
- A standard readout electronics with pole-zero implementation was also used [3]

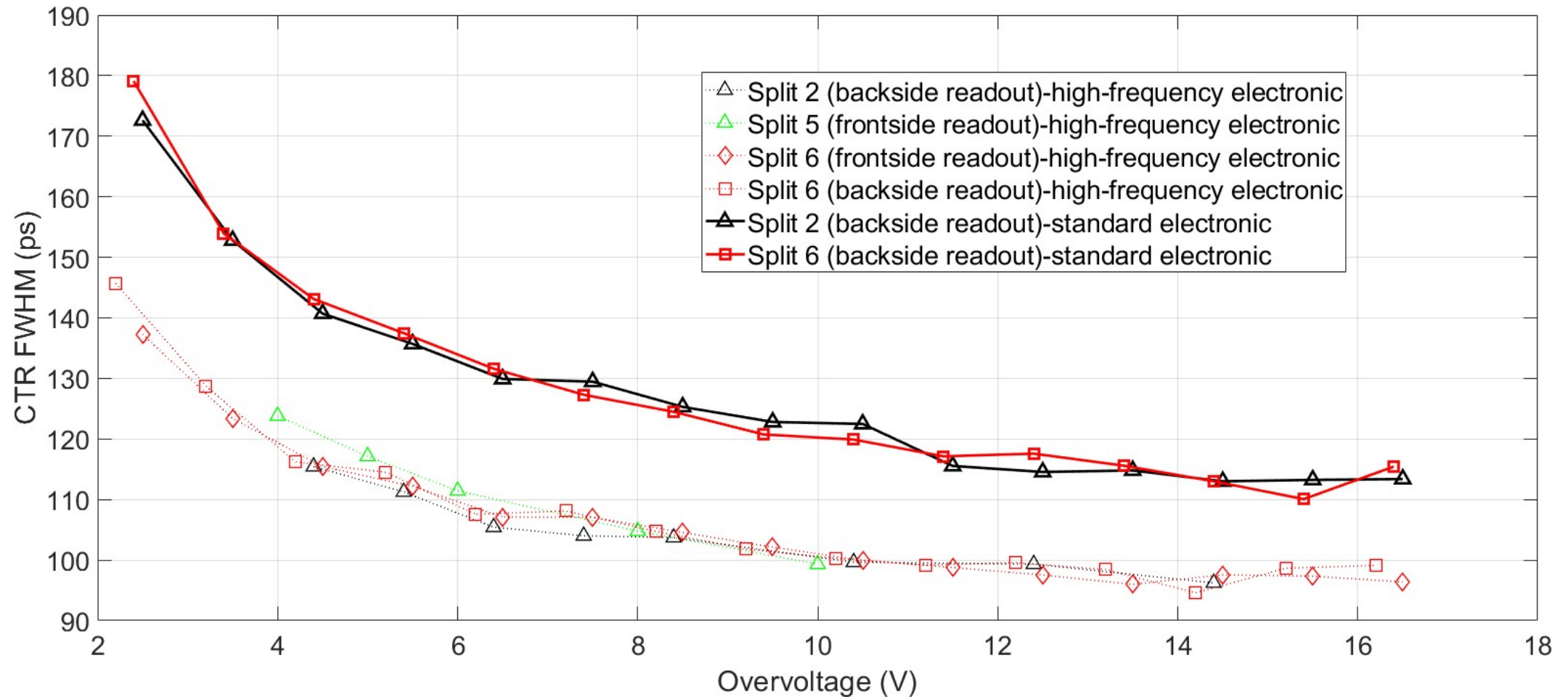
[1] J. W. Cates *et al*, "Improved single photon time resolution for analog SiPMs with front end readout that reduces the influence of electronic noise", 2018, *Phys. Med. Biol.* **63** 185022

[2] S Gundacker *et al*, "High-frequency SiPM readout advances measured coincidence time resolution limits in TOF-PET" 2019, *Phys. Med. Biol.* **64** 055012

[3] Gola, Alberto *et al*. "Analog Circuit for Timing Measurements With Large Area SiPMs Coupled to LYSO Crystals". *IEEE Transactions on Nuclear Science* **60** (2011): 1296-1302

Coincidence time resolution (CTR) using a
SiPM of $4 \times 4 \text{ mm}^2$ of active area

$2.76 \times 2.76 \times 18 \text{ mm}^3$ LYSO:Ce crystal



Remarks and Conclusions

- A new Near-Ultraviolet sensitive Deep Junction (NUV-DJ) SiPMs technology is under development on FBK
- Several 8-inch wafers were manufactured in an external silicon foundry and the main layout and process split were tested in the laboratory
- The measured breakdown voltage in all the wafers was aligned with the expected values from the TCAD simulations with a percent error less than 5%
- For the process split 2, the DCR at 20 °C was less than 80 kcps/mm² for 65% PDE at 420nm which correspond of about 6 V of overvoltage (OV)
- The direct crosstalk probability for split 2 and 5 was less than 2% for 65% PDE, confirming the effectiveness of the new SPAD structure and the good optical isolation between microcells

Remarks and Conclusions

- The PDE showed unprecedented values of about 70% (including a nominal fill factor of 80.8%), at 420 nm of wavelength and 9 V of excess bias for Thin epi thicknesses
- Moreover, we measured a SPTR of 60 ps FWHM at 20 V of excess bias, for a 4x4 mm² SiPM and a CTR of less than 100 ps FWHM with a High Frequency readout using a 2.76x2.76x18 mm³ LYSO:Ce crystal at 10 V of excess bias
- The measured CTR using standard readout electronics showed excellent values (about 115 ps FWHM at OV greater than 10 V)
- These results are state-of-art as regards timing and PDE, thus very interesting for ToF-PET applications or in an experiment where a high PDE in the NUV region is a requirement

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